

### **REMARKS**

Applicants appreciate the consideration of the present application afforded by the Examiner. Claims 1 and 2 remain pending. Claim 1 is independent. Favorable reconsideration and allowance of the present application are respectfully requested in view of the following remarks.

#### ***Claim Rejections - 35 U.S.C. §102***

Claims 1 and 2 stand rejected under 35 U.S.C. §102(a) as allegedly being anticipated by U.S. Patent No. 6,652,799 to Seng et al. ("Seng"). Applicants submit the Examiner has failed to establish a *prima facie* case of anticipation and traverse the rejection.

In order to establish a *prima facie* case of anticipation under 35 U.S.C. §102, the cited reference must teach or suggest each and every element in the claims. *See M.P.E.P. §2131; M.P.E.P. §706.02*. Accordingly, if the cited reference fails to teach or suggest one or more claimed elements, the rejection is improper and must be withdrawn.

Independent claim 1 recites "*a method of resin sealing of an electronic component in a cavity using an upper mold, a lower mold opposite to said upper mold, a middle mold provided between said upper mold and said lower mold and including a through hole into which said lower mold can be inserted,*" comprising *inter alia* "*attaching to said upper mold an unsealed substrate having said electronic component mounted thereon; inserting said lower mold into said through hole of said middle mold;*" and "*covering a whole surface of said cavity with said release film while said release film is sandwiched between said lower mold and said middle mold.*" Applicants submit that Seng does not expressly disclose at least all of these features of independent claim 1.

Seng is directed towards a method for molding semiconductor components with a molding apparatus including a pair of opposing mold chases 12 and 14 with mating mold cavities 16 and 18. *See col. 4, lines 14-24, Figure 1A*. Also included is a movable pot 26 which moves from an open position (Figure 1A) to a closed position (Figure 1B) when the mold chases are brought together. The movable pot includes a reservoir 30 which contains the molding

compound which is moved into the molding cavities by the action of a plunger mechanism 32. *See col. 4, lines 38-59.*

In the Office Action, the Examiner notes that he considers the movable pot of Seng to constitute the middle mold of the instant invention. Applicants respectfully submit that this is an unreasonable interpretation of Seng, especially in view of the current amendment to claim 1. First, Applicants submit that the movable pot of Seng is part of the molding compound supply system of Seng and is not actually itself a mold. From Figures 4A and 4B of Seng it is clear that the resin ultimately encasing the semiconductor elements is not molded in any way by the movable pot.

Secondly, the Examiner's characterization of the movable pot as a middle mold "*provided between said upper mold and said lower mold*" is unreasonable as Seng clearly shows the movable pot as provided within the structure of the lower mold chase and not between the upper and lower mold chases. *See Figures 1A and 1B.*

Third, independent claim 1 recites an upper mold, a lower mold, and a middle mold including a through hole into which said lower mold can be inserted. In contradistinction, the movable pot of Seng does not include a through hole into which the lower mold can be inserted, as claimed. Additionally, claim 1 recites "*covering a whole surface of said cavity with said release film while said release film is sandwiched between said lower mold and said middle mold.*" Applicants can find no basis in Seng, nor has the Examiner supplied an explanation of his interpretation of Seng, whereby during the process in Seng a release film is in any way sandwiched between the movable pot 26 and mold chase 12.

Therefore, at least because Seng fails to teach or suggest each and every claimed element, independent claim 1 is distinguishable from the prior art. Dependent claim 2 is also distinguishable from the prior art at least due to its dependence from claim 1, directly or indirectly. Accordingly, Applicant respectfully requests that the rejection of claims 1-2 under 35 U.S.C. § 102(a) be withdrawn.

**CONCLUSION**

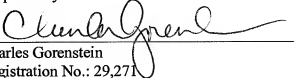
All objections and rejections raised in the Office Action having been addressed, it is respectfully submitted that the present application is in condition for allowance. Notice of same is earnestly solicited.

Should there be any outstanding matters that need to be resolved in the present application, the Examiner is respectfully requested to contact John R. Sanders Reg. No. 60,166 at the telephone number of the undersigned below, to conduct an interview in an effort to expedite prosecution in connection with the present application.

If necessary, the Commissioner is hereby authorized in this, concurrent, and future replies to charge payment or credit any overpayment to Deposit Account No. 02-2448 for any additional fees required under 37.C.F.R. §§1.16 or 1.14; particularly, extension of time fees.

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Respectfully submitted,

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